



Reflow Soldering Profile

Limiting Values*

The below temperature profile for moisture sensitivity characterization is based on the IPC/JEDEC joint industry standard: J-STD-020C.

Profile Feature	SnPb eutectic assembly	Pb-free assembly
Average ramp-up rate (T_{smax} to T_p)	3 °C/s maximum	3 °C/s maximum
Preheat		
Temperature minimum (T_{smin})	100 °C	150 °C
Temperature maximum (T_{smax})	150 °C	200 °C
Time (t_{smin} to t_{smax})	60 s to 120 s	60 s to 180 s
Time maintained above		
Temperature (T_L)	183 °C	217 °C
Time (t_L)	60 s to 150 s	60 s to 150 s
Peak/classification temperature (T_p)	235 °C	260 °C
Number of allowed reflow cycles	3	3
Time within 5 °C of actual peak temperature (t_p)	10 s to 30 s	20 s to 40 s
Ramp-down rate	6 °C/s maximum	6 °C/s maximum
Time 25 °C to peak temperature	6 minutes maximum	8 minutes maximum

* applicable for general application devices

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